



ACE2308E N-Channel 30-V MOSFET

Features

- Low $r_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed

Applications

- Power Routing
- Li Ion Battery Packs
- Level Shifting and Driver Circuits

Absolute Maximum Ratings

Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^a	I_D	$T_A=25^\circ\text{C}$	3.5
		$T_A=70^\circ\text{C}$	2.8
Pulse Drain Current ^b	I_{DM}	15	A
Continuous Source Current (Diode Conduction) ^a	I_S	1.9	A
Power Dissipation ^a	P_D	$T_A=25^\circ\text{C}$	1.3
		$T_A=70^\circ\text{C}$	0.8
Operating Temperature / Storage Temperature	T_J/T_{STG}	-55/150	$^\circ\text{C}$

*1 $P_w \leq 10 \mu\text{s}$, Duty cycle $\leq 1\%$

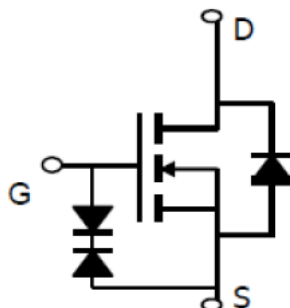
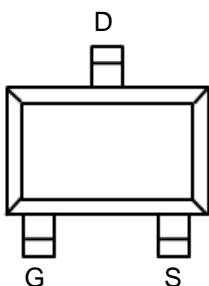
*2 When mounted on a 1*0.75*0.062 inch glass epoxy board%

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$R_{\theta JA}$	$t \leq 10 \text{ sec}$	100
		Steady State	166

Packaging Type

SOT-23-3





ACE2308E N-Channel 30-V MOSFET

Ordering information

ACE2308EBM + H

└─┬─┘	Halogen - free
└─┬─┘	Pb - free
└─┬─┘	BM : SOT-23-3

Electrical Characteristics

($T_A=25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.4			V
Gate-Body Leakage	$V_{GS(th)}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 10	μA
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			25	
On-State Drain Current a	$I_{D(on)}$	$V_{DS} = 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	5			A
Drain-Source On-Resistance a	$r_{DS(on)}$	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$			60	$\text{m}\Omega$
		$V_{GS} = 2.5 \text{ V}, I_D = 2.4 \text{ A}$			82	
Forward Transconductance a	gfs	$V_{DS} = 15 \text{ V}, I_D = 2.8 \text{ A}$		12		S
Diode Forward Voltage a	VSD	$I_S = 1 \text{ A}, V_{GS} = 0 \text{ V}$		0.69		V
Dynamic b						
Total Gate Charge	Q_g	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$		6		nC
Gate-Source Charge	Q_{gs}			1.0		
Gate-Drain Charge	Q_{gd}			2.0		
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = 15 \text{ V}, R_L = 3.6 \Omega, I_D = 3 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$		8		nS
Rise Time	t_r			21		
Turn-Off Delay Time	$t_{d(off)}$ *			48		
Fall Time	t_f			26		
Input Capacitance	C_{iss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		417		pF
Output Capacitance	C_{oss}			77		
Reverse Transfer Capacitance	C_{rss}			68		

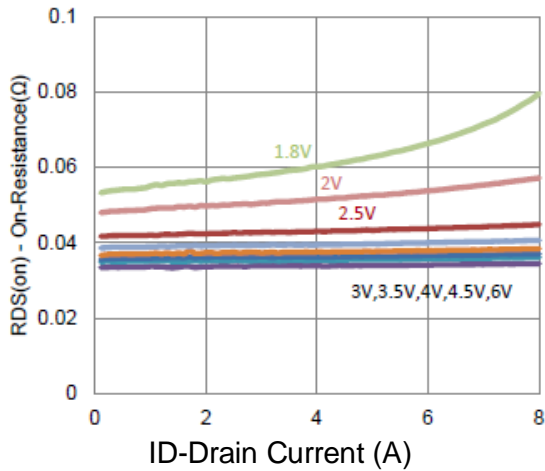
Notes

- Pulse test: $PW \leq 300\mu\text{s}$ duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.

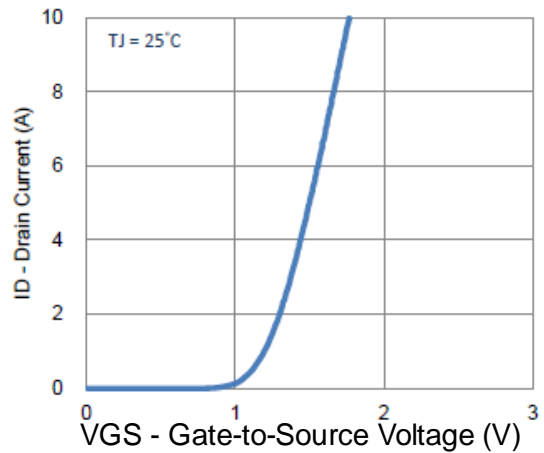


ACE2308E N-Channel 30-V MOSFET

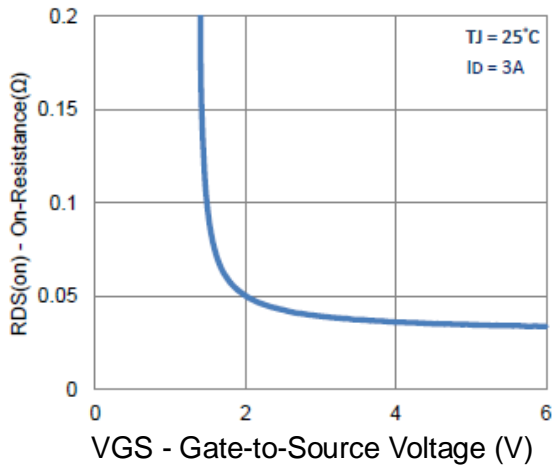
Typical Performance Characteristics



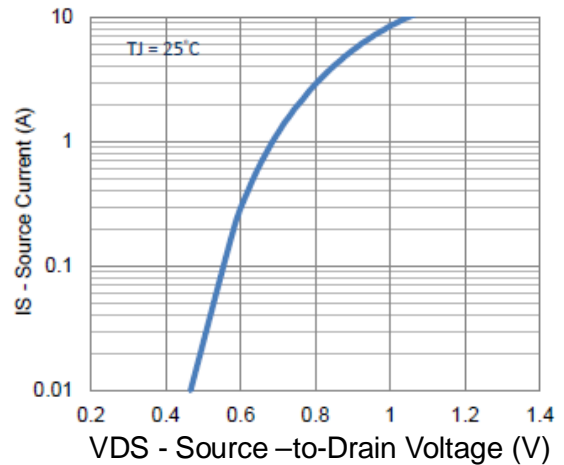
1. On-Resistance vs. Drain Current



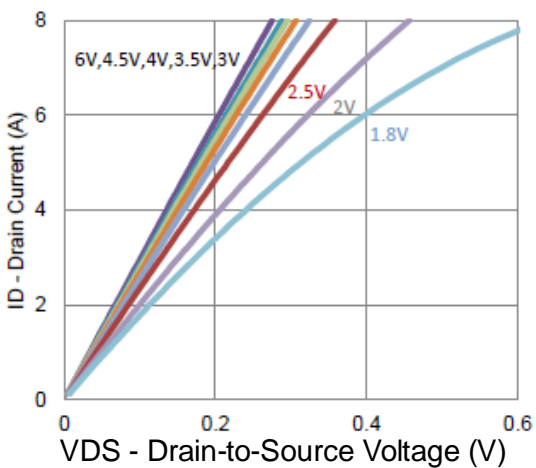
2. Transfer Characteristics



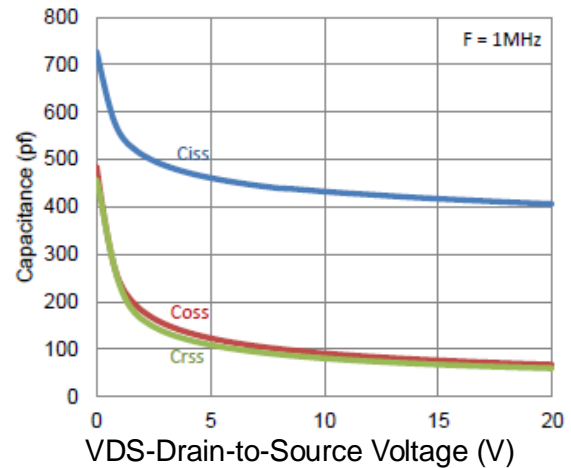
3. On-Resistance vs. Gate-to-Source Voltage



4. Drain-to-Source Forward Voltage



5. Output Characteristics

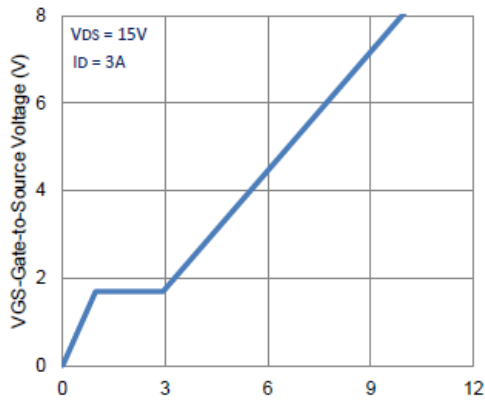


6. Capacitance

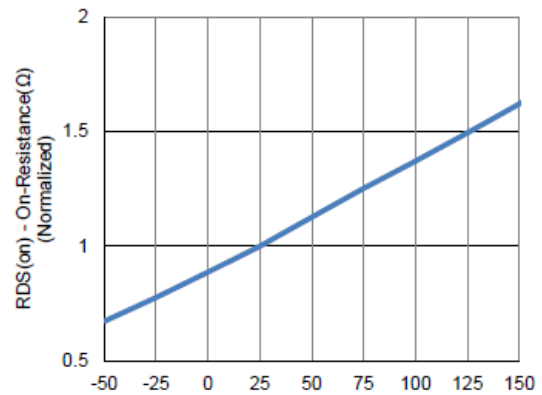


ACE2308E N-Channel 30-V MOSFET

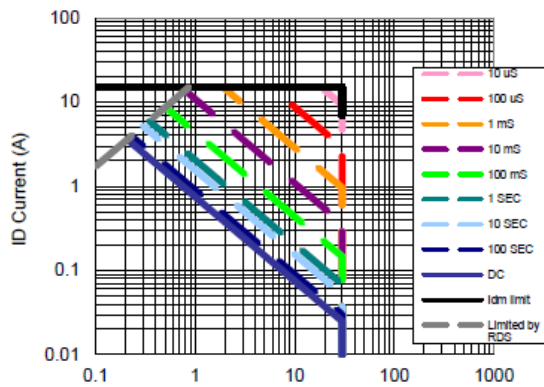
Typical Performance Characteristics



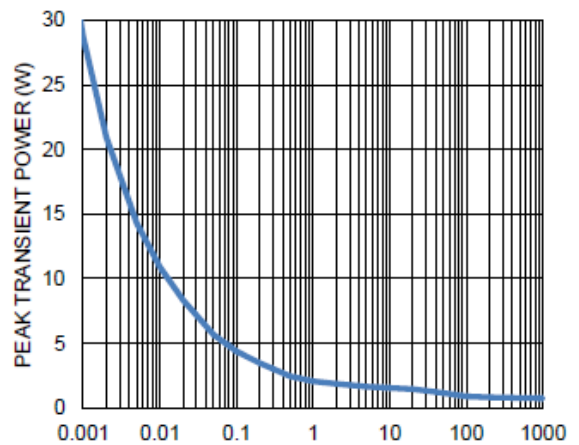
Qg - Total Gate Charge (nC)
7. Gate Charge



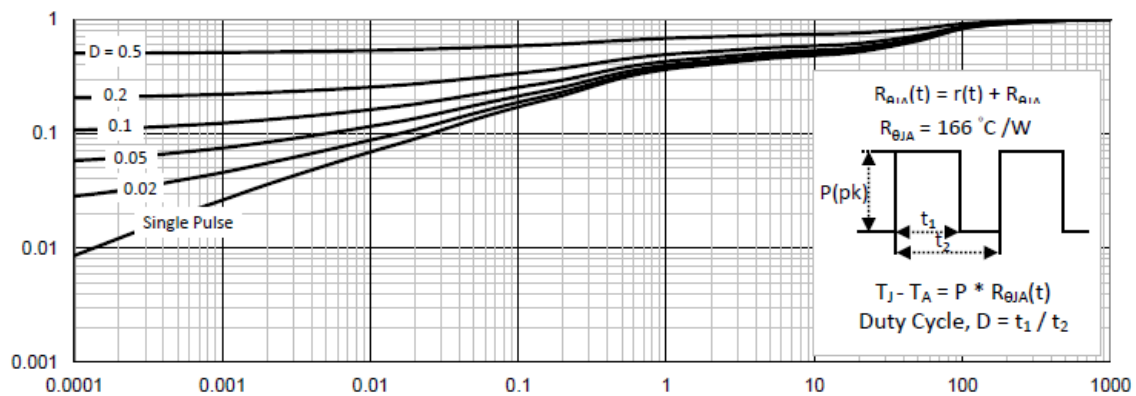
TJ-Junction Temperature(°C)
8. Normalized On-Resistance Vs
Junction Temperature



VgS Drain to Source Voltage (V)
9. Safe Operating Area



t1 TIME (sec)
10. Single Pulse Maximum Power Dissipation



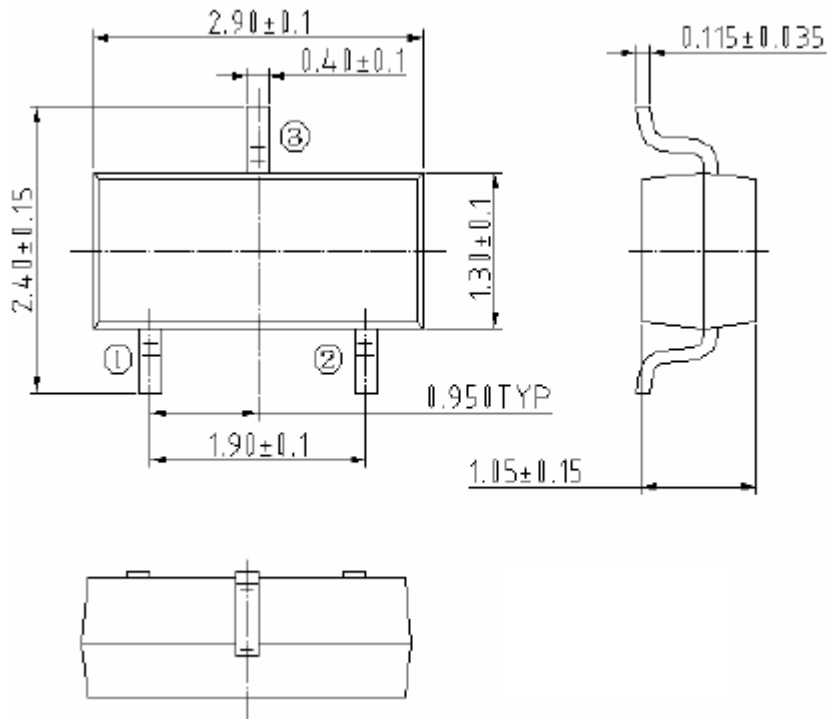
t1 TIME (sec)
11. Normalized Thermal Transient Junction to Ambient



ACE2308E N-Channel 30-V MOSFET

Packing Information

SOT-23-3



SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.935	0.95	1.10
A1	0.01		0.10
A2	0.85	0.90	0.925
B	0.30	0.40	0.50
C	0.10	0.15	0.25
D	2.70	2.90	3.10
E	2.60	2.80	3.00
E1	1.40	1.60	1.80
e	0.95BSC		
e1	1.90BSC		
L	0.30	0.40	0.60
L1	0.60REF		
L2	0.25BSC		
R	0.10		
Θ	0°	4°	8°
$\Theta 1$	7°NOM		

U

nit: mm



ACE2308E N-Channel 30-V MOSFET

Notes

ACE does not assume any responsibility for use as critical components in life support devices or systems without the express written approval of the president and general counsel of ACE Electronics Co., LTD. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ACE Technology Co., LTD.
<http://www.ace-ele.com/>